

D1 an X-Y table for displacing a position of a multilayer printed wiring board, wherein a wavelength of said processing laser source is between 720nm and a minimum wavelength of the laser source, or between 6000nm and a maximum wavelength of the laser source, and said processing laser source forms a via hole exposing a conductive in an interlayer resin.

D2 8. (Amended) The multilayer printed wiring board manufacturing apparatus according to Claim 5 or 7, wherein said harmonic wave generating means is a non-linear optical crystal which reflects the processing laser to the harmonic wave emitting side and gives thereto the function to transmitting harmonic wave.

D3 12. (Thrice Amended) A laser processing apparatus comprising a processing laser source, harmonic wave generating means for converting a laser beam oscillated from said processing laser source to a shortened wavelength beam of a second harmonic wave, wherein said harmonic wave generating means is a non-linear optical crystal which reflects the processing laser to the harmonic wave emitting side and gives thereto the function to transmitting harmonic wave, and a scanning head for deflecting a direction of the laser beam to X-Y directions or an X-Y table for displacing a position of a work piece to be processed, wherein a wavelength of said processing laser source is between 720nm and a minimum wavelength of the laser source, or between 6000nm and a maximum wavelength of the laser source, and said processing laser source forms a via hole exposing a conductive in an interlayer resin layer.

See the attached Appendix for the changes made to effect the above claims.

Please enter the following new claims.

~~26~~ (New) The multilayer printed wiring board manufacturing apparatus according to

Claim 5, wherein said via hole is formed by focussed spot diameter.

~~27~~ (New) The multilayer printed wiring board manufacturing apparatus according to

Claim 11, wherein said via hole is formed by focussed spot diameter.--